

6367254 MOTOROLA SC (XSTRS/R F)

96D 80742 D

MOTOROLA SEMICONDUCTOR TECHNICAL DATA

BUS48P BUS48AP

T-33-13

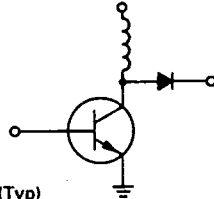
SWITCHMODE II^A SERIES NPN SILICON POWER TRANSISTORS

The BUS 48P/BUS 48AP transistors are designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line-operated switch-mode applications such as:

- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls
- Deflection Circuits

Fast Turn-Off Times

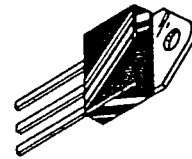
60 ns Inductive Fall Time—25°C (Typ)
120 ns Inductive Crossover Time—25°C (Typ)



Operating Temperature Range -65 to +175°C

100°C Performance Specified for:
Reverse-Biased SOA with Inductive Loads
Switching Times with Inductive Loads
Saturation Voltages
Leakage Currents (125°C)

15 AMPERES NPN SILICON POWER TRANSISTORS
400 and 450 VOLTS (BVCEO)
850 - 1000 VOLTS (BVCEV)
150 WATTS



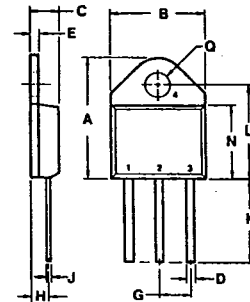
MAXIMUM RATINGS

Rating	Symbol	BUS 48P	BUS 48AP	Unit
Collector-Emitter Voltage	V _{CEO(sus)}	400	450	Vdc
Collector-Emitter Voltage	V _{CEV}	850	1000	Vdc
Emitter Base Voltage	V _{EB}	7		Vdc
Collector Current - Continuous	I _C	15		Adc
Collector Current - Peak (1)	I _{CM}	30		
Collector Current - Overload	I _{OI}	60		
Base Current - Continuous	I _B	5		Adc
Base Current - Peak (1)	I _{BM}	20		
Total Power Dissipation - T _C = 25°C	P _D	150		Watts
Total Power Dissipation - T _C = 100°C		75		
Derate above 25°C		1.0		W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +175		°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R _{θJC}	1.0	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	T _L	275	°C

(1) Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.



STYLE 1:

1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	20.32	21.08	0.800	0.830
B	15.49	15.90	0.610	0.626
C	4.19	5.08	0.165	0.200
D	1.02	1.65	0.040	0.065
E	1.35	1.65	0.053	0.065
G	5.21	5.72	0.205	0.225
H	2.41	3.20	0.095	0.126
J	0.38	0.64	0.015	0.025
K	12.70	15.49	0.500	0.610
L	15.88	16.51	0.625	0.650
N	12.19	12.70	0.480	0.500
Q	3.94	4.19	0.155	0.165

CASE 340-01
TO-218AC



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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS (1)

Collector-Emitter Sustaining Voltage (Table 1) (I _C = 200 mA, I _B = 0) L = 25 mH	BUS48P BUS48AP	V _{CEO(sus)}	400 450	-	-	V _{dc}
Collector Cutoff Current (V _{CEV} = Rated Value, V _{BE(off)} = 1.5 V _{dc}) (V _{CEV} = Rated Value, V _{BE(off)} = 1.5 V _{dc} , T _C = 125°C)		I _{CEV}	-	-	0.2 2.0	mAdc
Collector Cutoff Current (V _{CE} = Rated V _{CEV} , R _{BE} = 10 Ω)	T _C = 25°C T _C = 125°C	I _{CER}	-	-	0.5 3.0	mAdc
Emitter Cutoff Current (V _{EB} = 5 V _{dc} , I _C = 0)		I _{EBO}	-	-	0.1	mAdc
Emitter-base breakdown Voltage (I _E = 50 mA - I _C = 0)		V _{VEBO}	7.0	-	-	V _{dc}

SECOND BREAKDOWN

Second Breakdown Collector Current with Base Forward Biased	I _{S/b}	See Figure 12			
Clamped Inductive SOA with Base Reverse Biased	RBSOA	See Figure 13			

ON CHARACTERISTICS (1)

DC Current Gain (I _C = 10 Adc, V _{CE} = 5 V _{dc}) (I _C = 8 Adc, V _{CE} = 5 V)	BUS48 BUS48A	h _{FE}	8	-	-	
Collector-Emitter Saturation Voltage (I _C = 10 Adc, I _B = 2 Adc) (I _C = 15 Adc, I _B = 3 Adc) (I _C = 10 Adc, I _B = 2 Adc, T _C = 100°C) (I _C = 8 Adc, I _B = 1.6 Adc) (I _C = 12 Adc, I _B = 2.4 Adc) (I _C = 8 Adc, I _B = 1.6 Adc, T _C = 100°C)	BUS48P BUS48AP	V _{CE(sat)}	-	-	1.5 5.0 2.0 1.5 5.0 2.0	V _{dc}
Base-Emitter Saturation Voltage (I _C = 10 Adc, I _B = 2 Adc) (I _C = 10 Adc, I _B = 2 Adc, T _C = 100°C) (I _C = 8 Adc, I _B = 1.6 Adc) (I _C = 8 Adc, I _B = 1.6 Adc, T _C = 100°C)	BUS48P BUS48AP	V _{BE(sat)}	-	-	1.6 1.6 1.6 1.6	V _{dc}

DYNAMIC CHARACTERISTICS

Output Capacitance (V _{CB} = 10 V _{dc} , I _E = 0, f _{test} = 100 KHz)	C _{ob}	-	-	350	pF
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SWITCHING CHARACTERISTICS

Resistive Load (Table 1)

Delay Time	(V _{CC} = 250 V _{dc} , I _C = 10 A, I _{B1} = 2.0 A, t _p = 30 μs, Duty Cycle 2%, V _{BE(off)} = 5 V)	t _d	-	0.1	0.2	μs
Rise Time		t _r	-	0.4	0.7	
Storage Time		t _s	-	1.3	2.0	
Fall Time		t _f	-	0.2	0.4	

Inductive Load, Clamped (Table 1)

Storage Time	(I _{C(pk)} = 10 A, I _{B1} = 2.0 A, V _{BE(off)} = 5 V, V _{CE(c1)} = 250 V)	(T _C = 25°C)	t _{sv}	-	1.3	-	μs
Fall Time			t _{fi}	-	0.06	-	
Storage Time		(T _C = 100°C)	t _{sv}	-	1.5	2.5	
Crossover Time			t _c	-	0.3	0.6	
Fall Time			t _{fi}	-	0.17	0.35	

(1) Pulse Test: PW = 300 μs, Duty Cycle ≤ 2%.



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DC CHARACTERISTICS

FIGURE 1 - DC CURRENT GAIN

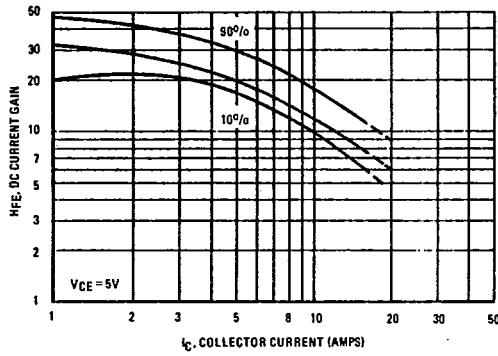


FIGURE 2 - COLLECTOR SATURATION REGION

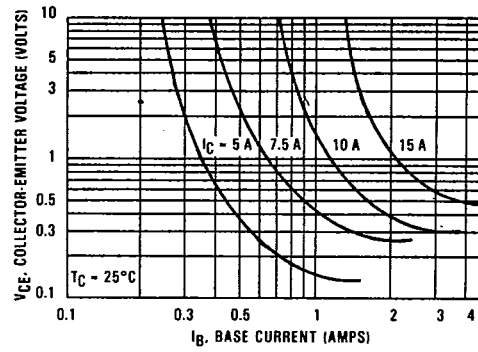


FIGURE 3 - COLLECTOR-EMITTER SATURATION VOLTAGE

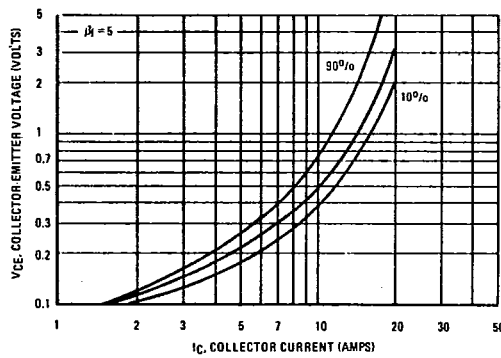


FIGURE 4 - BASE-EMITTER VOLTAGE

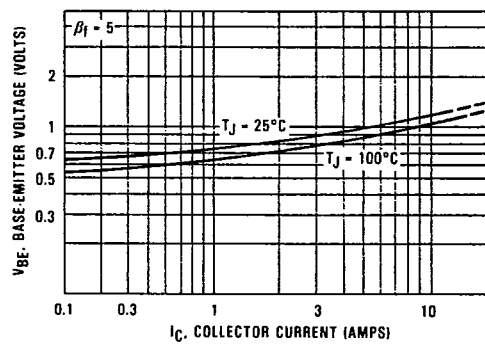


FIGURE 5 - COLLECTOR CUTOFF REGION

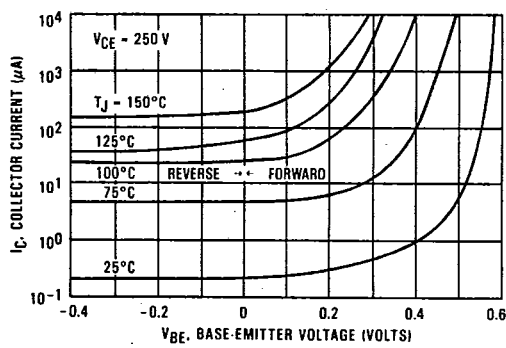
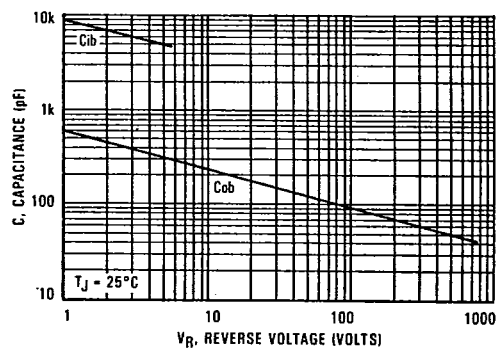


FIGURE 6 - CAPACITANCE



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TABLE 1 - TEST CONDITIONS FOR DYNAMIC PERFORMANCE

	V _{CEO} (sus)	RBSOA AND INDUCTIVE SWITCHING	RESISTIVE SWITCHING
INPUT CONDITIONS	<p>+10 V 20 0 PW Varied to Attain I_C = 100 mA</p>		<p>TURN ON TIME I_{b1} I_{b1} Adjust to obtain the forced h_{FE} desired TURN OFF TIME Use inductive switching driver as the input to the resistive test circuit.</p>
CIRCUIT VALUES	<p>L_{coil} = 80 mH V_{CC} = 10 V R_{coil} = 0.7 Ω</p>	<p>L_{coil} = 180 μH R_{coil} = 0.05 Ω V_{CC} = 20 V V_{clamp} = 250 V R_g adjusted to attain desired I_{b1}</p>	<p>V_{CC} = 250 V R_L = 83 Ω Pulse Width = 10 μs</p>
TEST CIRCUITS	<p>INDUCTIVE TEST CIRCUIT</p>	<p>OUTPUT WAVEFORMS</p> <p>t₁ Adjusted to Obtain I_C</p> $t_1 = \frac{L_{coil} I_{C(pk)}}{V_{CC}}$ $t_2 = \frac{L_{coil} I_{C(pk)}}{V_{clamp}}$ <p>Test Equipment Scope - Tektronik 475 or Equivalent</p>	<p>RESISTIVE TEST CIRCUIT</p>

FIGURE 7 - INDUCTIVE SWITCHING MEASUREMENTS

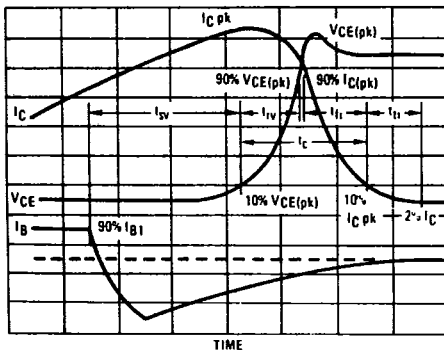
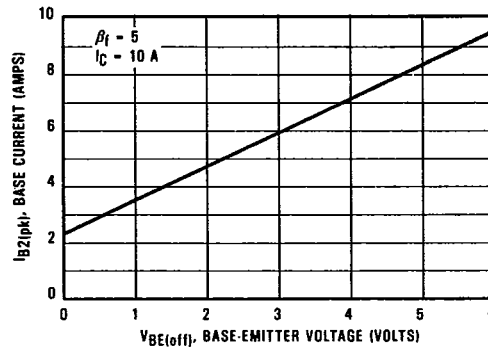


FIGURE 8 - PEAK-REVERSE CURRENT



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SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

- t_{sv} = Voltage Storage Time, 90% I_{B1} to 10% V_{clamp}
- t_{rv} = Voltage Rise Time, 10–90% V_{clamp}
- t_{fi} = Current Fall Time, 90–10% I_C
- t_{ti} = Current Tail, 10–2% I_C
- t_c = Crossover Time, 10% V_{clamp} to 10% I_C

An enlarged portion of the inductive switching waveforms

is shown in Figure 7 to aid in the visual identity of these terms.

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN-222:

$$P_{SWT} = 1/2 V_{CC} I_C (t_c) f$$

In general, $t_{rv} + t_{fi} \approx t_c$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_c and t_{sv}) which are guaranteed at 100°C.

INDUCTIVE SWITCHING

FIGURE 9 – STORAGE TIME, T_{sv}

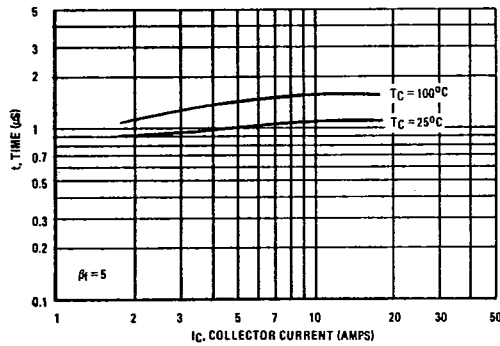


FIGURE 10 – CROSSOVER AND FALL TIMES

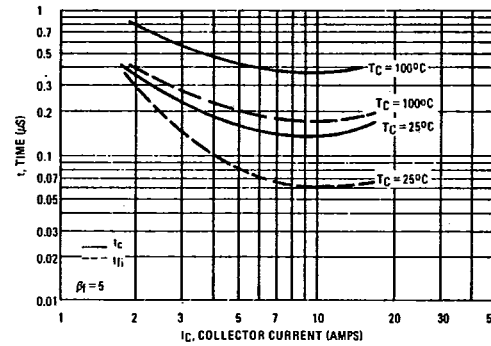


FIGURE 11a – TURN-OFF TIMES vs FORCED GAIN

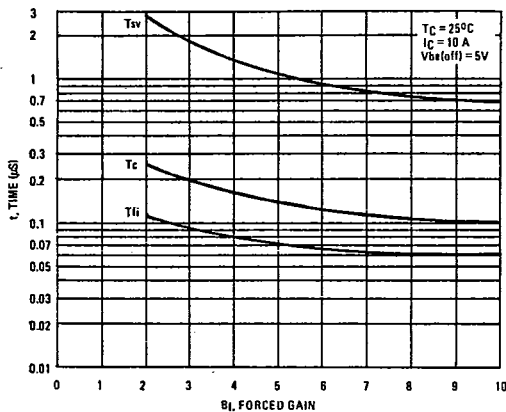
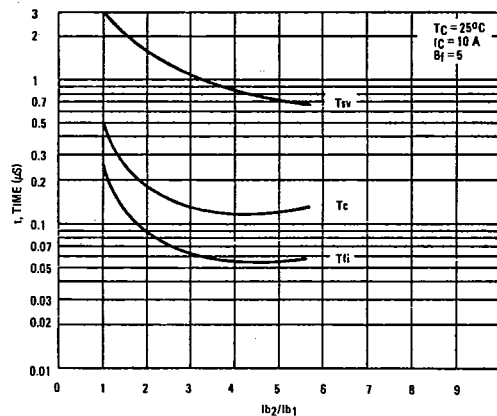


FIGURE 11b – TURN-OFF TIMES vs I_{b2}/I_{b1}



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The Safe Operating Area figures shown in Figures 12 and 13 are specified for these devices under the test conditions shown.

FIGURE 12 - FORWARD BIAS SAFE OPERATING AREA

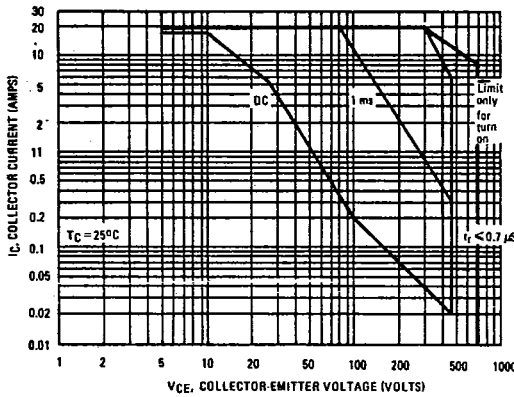


FIGURE 13 - REVERSE BIAS SAFE OPERATING AREA

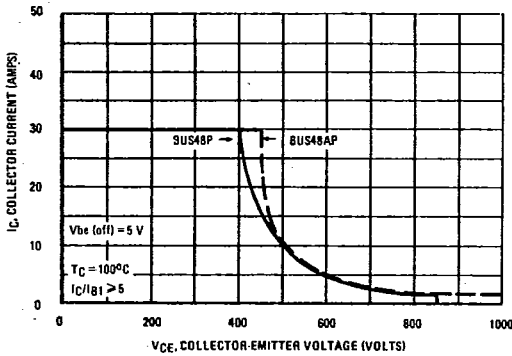
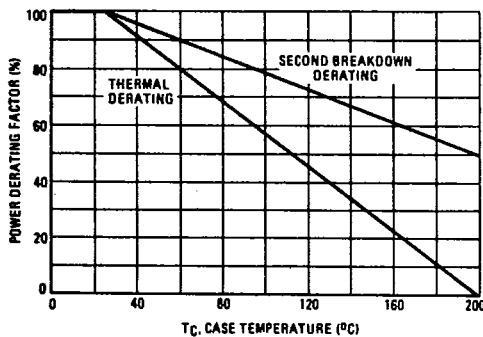


FIGURE 14 - POWER DERATING



SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C - V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_C = 25^\circ\text{C}$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \geq 25^\circ\text{C}$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 12 may be found at any case temperature by using the appropriate curve on Figure 14.

$T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current conditions during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 13 gives RBSOA characteristics.

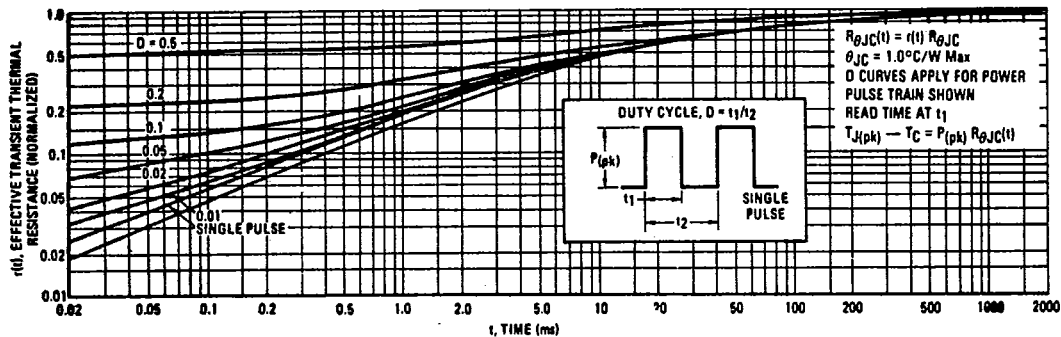


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FIGURE 15 - THERMAL RESPONSE



OVERLOAD CHARACTERISTICS

FIGURE 16 - RATED OVERLOAD SAFE OPERATING AREA (OLSOA)

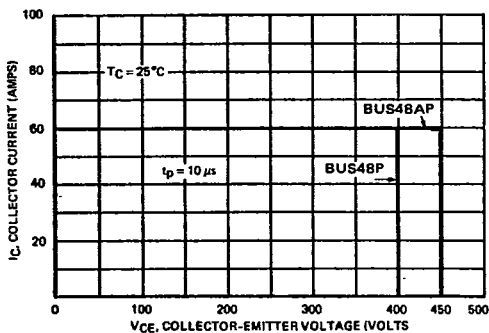
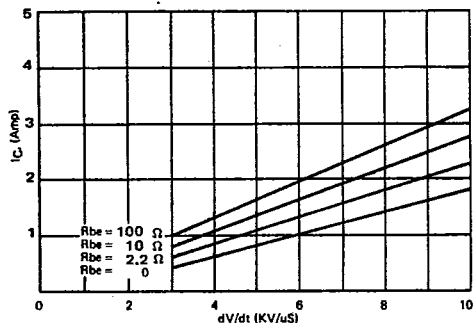


FIGURE 17 - $I_C = f(dV/dt)$



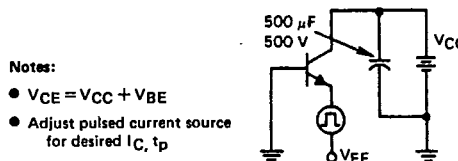
OLSOA

OLSOA applies when maximum collector current is limited and known. A good example is a circuit where an inductor is inserted between the transistor and the bus, which limits the rate of rise of collector current to a known value. If the transistor is then turned off within a specified amount of time, the magnitude of collector current is also known.

Maximum allowable collector-emitter voltage versus collector current is plotted for several pulse widths. (Pulse width is defined as the time lag between the fault condition and the removal of base drive.) Storage time of the transistor has been factored into the curve. Therefore, with bus voltage and maximum collector current known, Figure 16 defines the maximum time which can be allowed for fault detection and shutdown of base drive.

OLSOA is measured in a common-base circuit (Figure 18) which allows precise definition of collector-emitter voltage and collector current. This is the same circuit that is used to measure forward-bias safe operating area.

FIGURE 18 - OVERLOAD SOA TEST CIRCUIT



- Notes:
- $V_{CE} = V_{CC} + V_{BE}$
 - Adjust pulsed current source for desired I_C , t_p

